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Product Change Notification - SYST-03LNIL579
(Printer Friendly)

Date:	04 Mar 2016
Product Category:	8-bit Microcontrollers
Affected CPNs:	📄 📊
Notification subject:	Data Sheet - PIC32MZ Embedded Connectivity with Floating Point Unit (EF) Family Data Sheet Document Revision
Notification text:	SYST-03LNIL579

Microchip has released a new DeviceDoc for the PIC32MZ Embedded Connectivity with Floating Point Unit (EF) Family of devices. If you are using one of these devices please read the document located at PIC32MZ Embedded Connectivity with Floating Point Unit (EF) Family.

Notification Status: Final

Description of Change: In this revision, the Preliminary status was removed from the document footer. The revision also includes the following major changes, which are referenced by their respective chapter in Table C-2. In addition, minor updates to text and formatting were incorporated throughout the document. 1) 2.0 "Guidelines for Getting Started with 32-bit Microcontrollers": 2.9.1.3 "EMI/EMC/EFT (IEC 61000-4-4 and IEC 61000-4-2) Suppression Considerations" and Figure 2-5 were updated. 2) 4.0 "Memory Organization": The names of the Boot Flash Words were updated from BFxSEQ0 to BFxSEQ3 (see 4.1.1 "Boot Flash Sequence and Configuration Spaces"). The ABFxSEQx registers were removed from the Boot Flash Sequence and Configuration tables (see Table 4-2 and Table 4-3). 3) 7.0 "CPU Exceptions and Interrupt Controller": The Cache Error exception type was removed from the MIPS32 M-Class Microprocessor Core Exception Types (see Table 7-1). 4) 8.0 "Oscillator Configuration": The PLLODIV<2:0> bit value settings were updated in the SPLLCON register (see Register 8-3). 5) 12.0 "I/O Ports": The SIDL bit was removed from the CNCONx registers (see Table 12-4 through Table 12-21 and Register 12-3). 6) 20.0 "Serial Quad Interface (SQI)": The following bits were removed from the SQI1XCON1 register (see Table 20-1 and Register 20-1): DDRDATA, DDRDUMMY, DDRMODE, DDRADDR, and DDRCMD. The DDRMODE bit was removed from the SQI1CON register (see Table 20-1 and Register 20-4). 7) 28.0 "12-bit High-Speed Successive Approximation Register (SAR) Analog-to-Digital Converter (ADC)": A note was added to the SELRES<1:0> bits in the

ADCCON1 and ADCxTIME registers (see Register 28-1 and Register 28-27). The ADCID<2:0 bit values were updated in the ADCFSTAT register (see Register 28-22). 8) 34.0 "Special Features": The bit value definitions for the POSCGAIN<1:0> and SOSCGAIN<1:0> bits were updated (see Register 34-3). The Device ADC Calibration Word (DEVADCx) register was added (see Table 34-5 and Register 34-13). 9) 37.0 "Electrical Characteristics": The DC Characteristics: Operating Current (Idd) and Note 6 were updated (see Table 37-6). The DC Characteristics: Idle Current (Iidle) and Note 4 were updated (see Table 37-7). Parameter DC40m and Note 5 in the DC Characteristics: Power-down Current (Ipd) were updated (see Table 37-8). Parameter DO50 (Cosco) was removed from the Capacitive Loading Requirements on Output Pins (see Table 37-16). The Internal FRC Accuracy and Internal LPRC conditions were updated for 125ºC (see Table 37-20 and Table 37-21). Parameter SP15 and Note 5 of the SPIx Module Master Mode Timing Requirements were updated (see Table 37-30 and Table 37-31). The Temperature Sensor Specifications were updated (see Table 37-41). 10) 38.0 "Extended Temperature Electrical Characteristics": New chapter for Extended Temperature devices was added. 11) 39.0 "AC and DC Characteristics Graphs": The Typical Temperature Sensor Voltage graph was updated (see Figure 39-7). 12) 40.0 "Packaging Information": The package drawings and land pattern for the 64-Lead Plastic Quad Flat, No Lead Package (MR) were updated. 13) Appendix A: "Migrating from PIC32MX5XX/6XX/7XX to PIC32MZ EF": The Primary Oscillator Configuration section in the Oscillator Configuration Differences was updated (see Table A-1). 14) Appendix B: "Migrating from PIC32MZ EC to PIC32MZ EF": Boot Flashing aliasing was updated for PIC32MZ EF devices (see Table B-4).

Impacts to Data Sheet: None

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 04 Mar 2016

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachment(s):   PIC32MZ Embedded Connectivity with Floating Point Unit (EF) Family

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